

SEMiX223GD12Vc



SEMiX[®] 33c

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Features

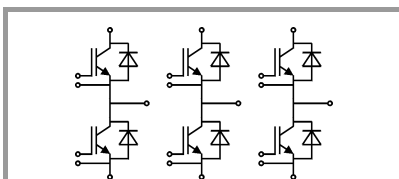
- Homogeneous Si
- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability
- UL recognised file no. E63532

Typical Applications*

- AC inverter drives
- UPS
- Electronic Welding

Remarks

- Case temperature limited to $T_C=125^\circ\text{C}$ max.
- Product reliability results are valid for $T_j=150^\circ\text{C}$
- Dynamic values apply to the following combination of resistors:
 $R_{Gon,main} = 2,9 \Omega$
 $R_{Goff,main} = 2,9 \Omega$
 $R_{G,x} = 2,2 \Omega$
 $R_{E,x} = 0,5 \Omega$



GD

Absolute Maximum Ratings

Symbol	Conditions	Values	Unit	
IGBT				
V_{CES}		1200	V	
I_C	$T_j = 175^\circ\text{C}$	$T_c = 25^\circ\text{C}$	323	A
		$T_c = 80^\circ\text{C}$	246	A
I_{Cnom}		225	A	
I_{CRM}	$I_{CRM} = 3 \times I_{Cnom}$	675	A	
V_{GES}		-20 ... 20	V	
t_{psc}	$V_{CC} = 600\text{ V}$ $V_{GE} \leq 15\text{ V}$ $V_{CES} \leq 1200\text{ V}$	$T_j = 125^\circ\text{C}$	10	μs
T_j		-40 ... 175	$^\circ\text{C}$	
Inverse diode				
I_F	$T_j = 175^\circ\text{C}$	$T_c = 25^\circ\text{C}$	263	A
		$T_c = 80^\circ\text{C}$	197	A
I_{Fnom}		225	A	
I_{FRM}	$I_{FRM} = 3 \times I_{Fnom}$	675	A	
I_{FSM}	$t_p = 10\text{ ms, sin } 180^\circ, T_j = 25^\circ\text{C}$	1161	A	
T_j		-40 ... 175	$^\circ\text{C}$	
Module				
$I_{t(RMS)}$	$T_{terminal} = 80^\circ\text{C}$	600	A	
T_{stg}		-40 ... 125	$^\circ\text{C}$	
V_{isol}	AC sinus 50Hz, $t = 1\text{ min}$	4000	V	

Characteristics

Symbol	Conditions	min.	typ.	max.	Unit
IGBT					
$V_{CE(sat)}$	$I_C = 225\text{ A}$ $V_{GE} = 15\text{ V}$ chipllevel	$T_j = 25^\circ\text{C}$	1.85	2.3	V
		$T_j = 150^\circ\text{C}$	2.3	2.55	V
V_{CE0}		$T_j = 25^\circ\text{C}$	0.94	1.04	V
		$T_j = 150^\circ\text{C}$	0.88	0.98	V
r_{CE}	$V_{GE} = 15\text{ V}$	$T_j = 25^\circ\text{C}$	4.0	5.6	$\text{m}\Omega$
		$T_j = 150^\circ\text{C}$	6.1	7.0	$\text{m}\Omega$
$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 9\text{ mA}$	5.5	6	6.5	V
I_{CES}	$V_{GE} = 0\text{ V}$ $V_{CE} = 1200\text{ V}$	$T_j = 25^\circ\text{C}$	0.1	0.3	mA
		$T_j = 150^\circ\text{C}$			mA
C_{ies}	$V_{CE} = 25\text{ V}$		13.5		nF
C_{oes}	$V_{GE} = 0\text{ V}$		1.33		nF
C_{res}			1.33		nF
Q_G	$V_{GE} = -8\text{ V} \dots +15\text{ V}$		2460		nC
R_{Gint}	$T_j = 25^\circ\text{C}$		3.33		Ω
$t_{d(on)}$	$V_{CC} = 600\text{ V}$ $I_C = 225\text{ A}$	$T_j = 150^\circ\text{C}$	470		ns
t_r	$V_{GE} = \pm 15\text{ V}$	$T_j = 150^\circ\text{C}$	72		ns
E_{on}	$R_{Gon} = 3.8\ \Omega$	$T_j = 150^\circ\text{C}$	19.9		mJ
$t_{d(off)}$	$R_{Goff} = 3.8\ \Omega$	$T_j = 150^\circ\text{C}$	665		ns
t_f	$di/dt_{on} = 3200\text{ A}/\mu\text{s}$ $di/dt_{off} = 2000\text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$	109		ns
E_{off}	$du/dt_{off} = 6600\text{ V}/\mu\text{s}$	$T_j = 150^\circ\text{C}$	27.2		mJ
$R_{th(j-c)}$	per IGBT			0.14	K/W

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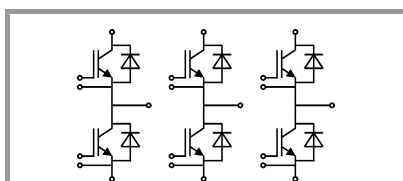
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Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Inverse diode						
$V_F = V_{EC}$	$I_F = 225 \text{ A}$ $V_{GE} = 0 \text{ V}$ chip	$T_j = 25^\circ\text{C}$		2.2	2.49	V
		$T_j = 150^\circ\text{C}$		2.1	2.4	V
V_{F0}		$T_j = 25^\circ\text{C}$	1.1	1.3	1.5	V
		$T_j = 150^\circ\text{C}$	0.7	0.9	1.1	V
r_F		$T_j = 25^\circ\text{C}$	3.6	3.9	4.4	m Ω
		$T_j = 150^\circ\text{C}$	4.7	5.4	5.9	m Ω
I_{RRM}	$I_F = 225 \text{ A}$	$T_j = 150^\circ\text{C}$		210		A
Q_{rr}	$di/dt_{off} = 3400 \text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$		39.4		μC
E_{rr}	$V_{GE} = -15 \text{ V}$ $V_{CC} = 600 \text{ V}$	$T_j = 150^\circ\text{C}$		16.4		mJ
$R_{th(j-c)}$	per diode				0.23	K/W
Module						
L_{CE}				20		nH
R_{CC+EE}	res., terminal-chip	$T_C = 25^\circ\text{C}$		0.7		m Ω
		$T_C = 125^\circ\text{C}$		1		m Ω
$R_{th(c-s)}$	per module			0.014		K/W
M_s	to heat sink (M5)		3		5	Nm
M_t	to terminals (M6)		2.5		5	Nm
						Nm
w					900	g
Temperatur Sensor						
R_{100}	$T_c=100^\circ\text{C}$ ($R_{25}=5 \text{ k}\Omega$)			$493 \pm 5\%$		Ω
$B_{100/125}$	$R_{(T)}=R_{100}\exp[B_{100/125}(1/T-1/T_{100})]$; T[K];			$3550 \pm 2\%$		K



GD

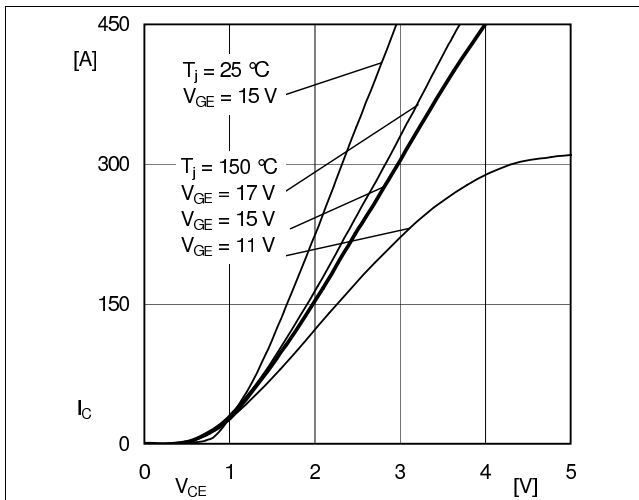


Fig. 1: Typ. output characteristic, inclusive $R_{CC'+EE'}$

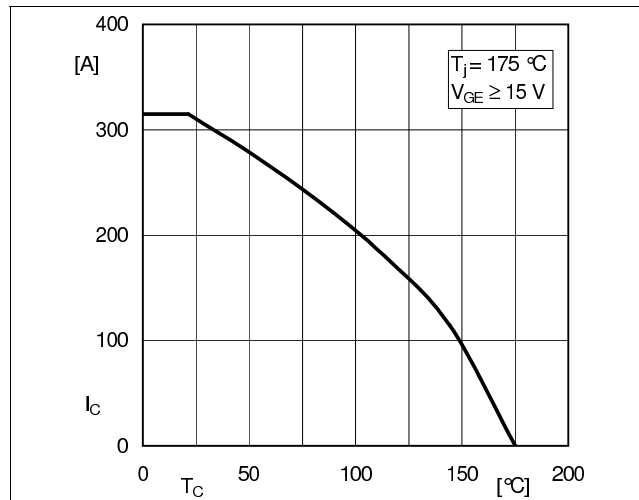


Fig. 2: Rated current vs. temperature $I_C = f(T_C)$

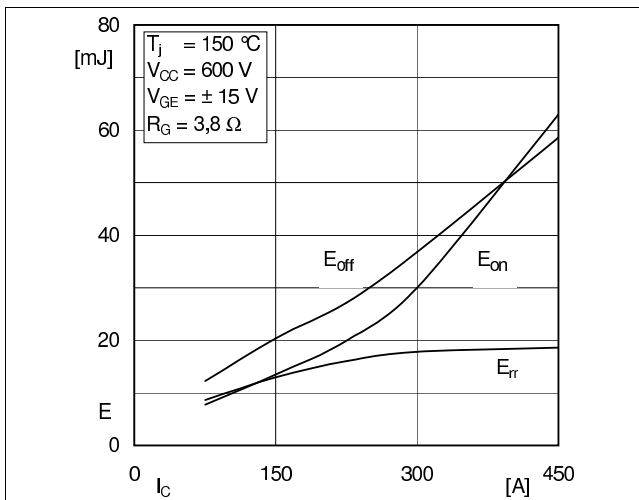


Fig. 3: Typ. turn-on /-off energy = $f(I_C)$

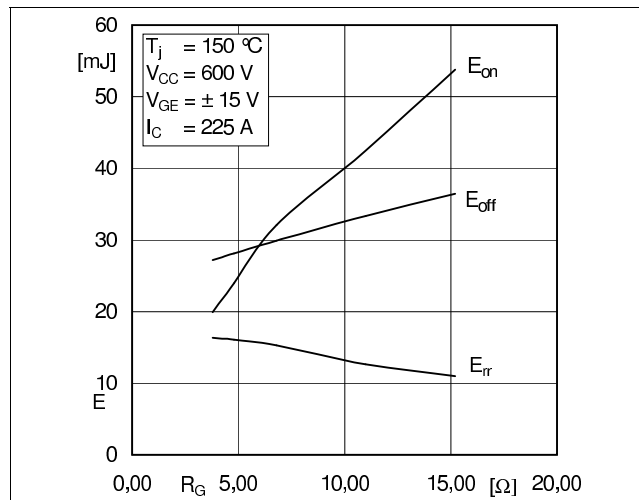


Fig. 4: Typ. turn-on /-off energy = $f(R_G)$

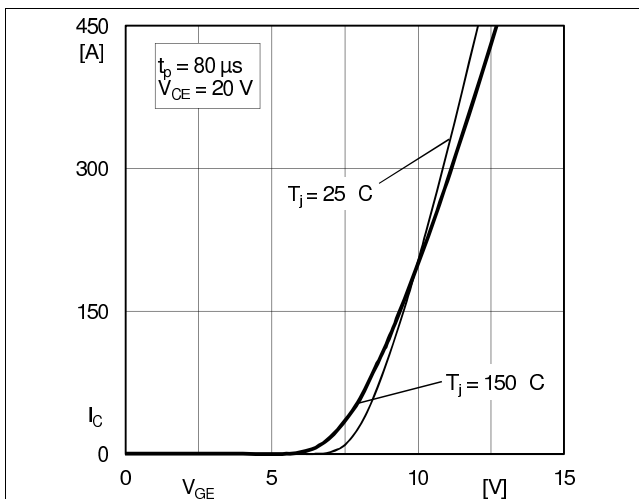


Fig. 5: Typ. transfer characteristic

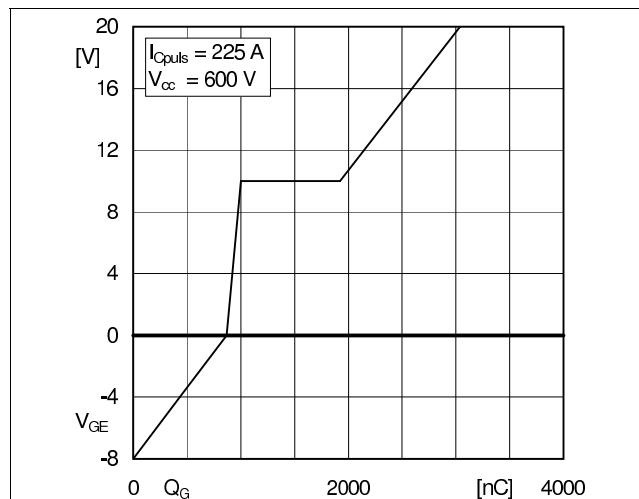


Fig. 6: Typ. gate charge characteristic

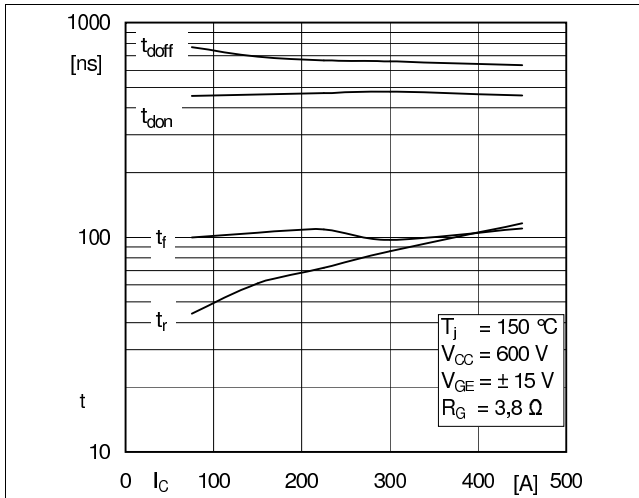


Fig. 7: Typ. switching times vs. I_C

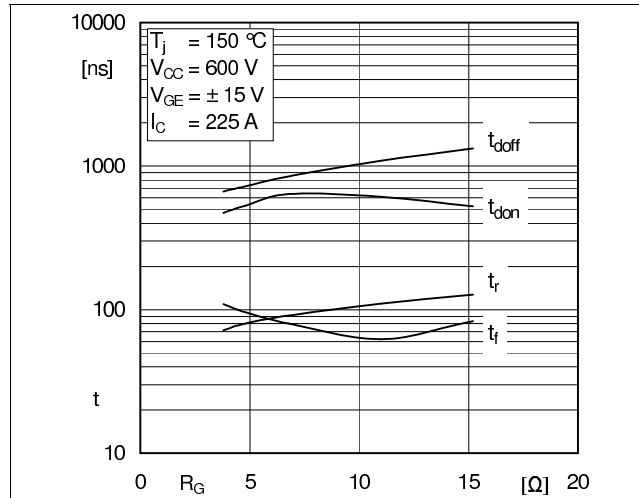


Fig. 8: Typ. switching times vs. gate resistor R_G

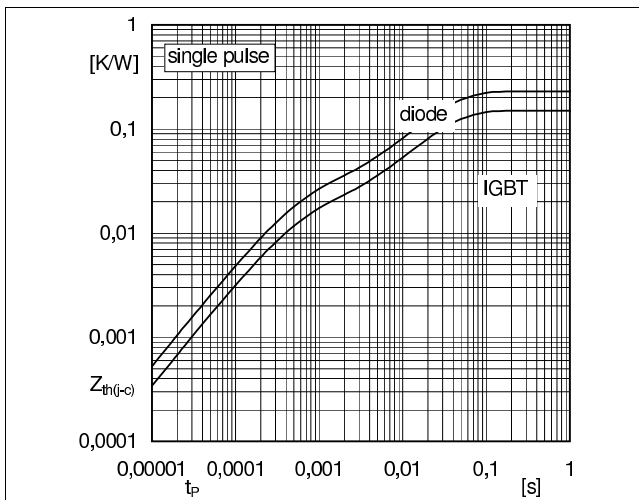


Fig. 9: Typ. transient thermal impedance

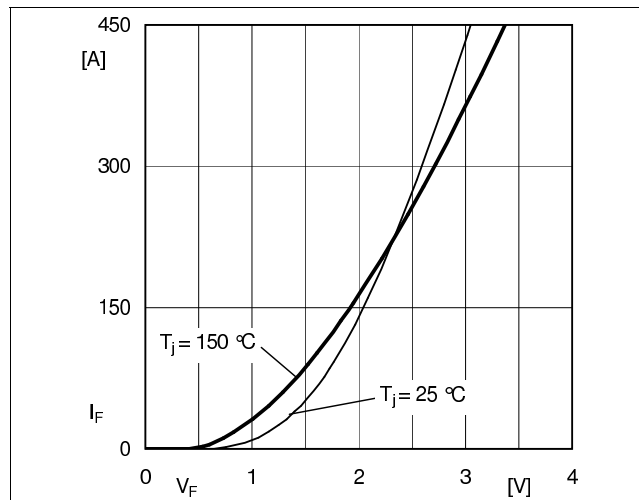


Fig. 10: Typ. CAL diode forward charact., incl. $R_{CC+EE'}$

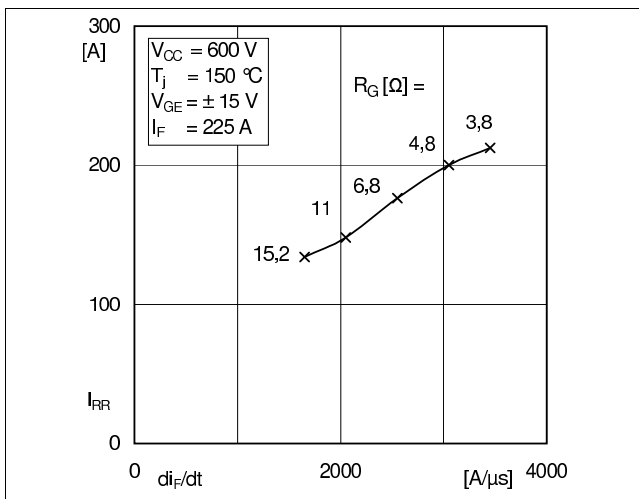


Fig. 11: Typ. CAL diode peak reverse recovery current

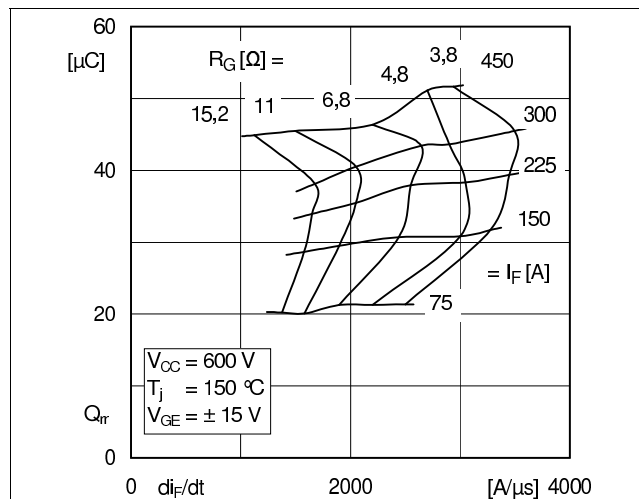


Fig. 12: Typ. CAL diode recovery charge

